AL300
Small Footprint High Precision Assembly Cell
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The machines of ficonTEC’s 300 series are small footprint yet high precision die bonders. They are designed to break down complex assembly processes into standardized recurring sub-processes for low cost of ownership.

Same as fully contained systems such as the 1000 or 2000 series the AL300 is build for industrial usage in production environments.

Typical Tasks
- Pick and place
- Die sorting
- Dispensing of adhesives
- UV curing
- Chip to chip bonding
- Chip to package assembly

ProcessControlMaster
Powerful Machine and Process Software
- Freely programmable machine processes
- User friendly user interface
- Line based process programming
- Recipe based management of process parameters
- Algorithms for active assembly
- SQL data base based storage of process parameters and flexible data import and export
- Component tracking
- Remote service and control via internet
- Same software on all ficonTEC machines for consistent look and feel of machine programming and operation
Built for Industrial Usage

- Rugged steel base production cell
- Hardware interlock circuit for safe operation
- Ergonomic HUI
- Integrated air and vac control
- Operation console for comfort access of basic machine function
- Cabinets for electrics and pneumatics
- Laser class 1 (for selected models)

Key Features

- Compact footprint
- Simple reconfiguration
- Reduced complexity
- Single task operation
- Fully automatic process
- Automatic calibration routine
- ProcessControlMaster: Extremely powerful and versatile machine software

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<th>Modules</th>
<th>Feature</th>
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| Dispensing Unit    | • For the dispensing of e.g. epoxies  
                     | • Controlled from within machine process |
| UV Curing Unit     | • For the illumination with UV light  
                     | • E.g. for curing of UV epoxies  
                     | • One (standard) or up to four illumination spots  
                     | • Controlled from within machine process |
| Pick-up Tool (PUT) | • Different PUTs available  
                     | • Glass, steel, rubber, plastic chosen for best application  
                     | • Operated with vacuum |

Machine Layout

- XYZRotZ main motion system
- Self damping granite bed
- Gelpak field (vacuum release)
- Cameras for machine calibration and component recognition
- Configurable bonding head
- Customized assembling chuck
What we do

ficonTEC designs and produces high precision production equipment for the assembling or testing of components.

We are the market leader when it comes to automated assembly or test of micro-optics or opto-electronics such as laser diode manufacture, medical technology, security and defense engineering, as well as telecommunication.

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